

**Invitation to International Competitive Bid
For the Procurement of Splicing Machine**

Floating Date: As of April 25, 2017

Closing Date: May 24, 2017

RFQ No. 3529076-2

REQUIREMENTS:

1. Ethio telecom intends to sign a Master Frame Agreement (MFA) contract for one (1) year with a possibility of extension up to a maximum of 3 years with the finally awarded bidder/bidders. Hence, ethio telecom invites all interested and eligible bidders by this **International Competitive Bid (ICB)** for the procurement of **Splicing Machine** with **RFQ No. 3529076-2**. The tender remains floating from **April 25, 2017 to May 24, 2017**.

Bid documents can be obtained from ethio telecom's Head Office, Room No. 201 during office hours upon payment of a non-refundable fee of Birr **100.00 (Birr One Hundred only)**.

2. Interested bidders are expected to fulfill the requirements stated here below:
 - a) Bid security;
 - b) Availability of letter of authorization to sign the bid offers;
 - c) Anti-bribery pledge form;

All local firms organized and licensed under the laws of Ethiopia that qualify to bid are invited to participate in this invitation to bids and have to fulfill the following requirements in addition to the above mentioned requirements.

- d) Bidders should have a valid and renewed trade license for the year;
 - e) Bidders should have VAT registration certificate.
3. All bids must be accompanied by a bid security in the amount of **Birr 100,000.00 (Birr One Hundred Thousand only)**.
 - 3.1 The bid bond shall be furnished in one of the following forms:
 - a) Certified Cheque /CPO issued by a recognized domestic bank or
 - b) Bond issued by and/or confirmed through a recognized/reputable domestic bank.
 - 3.2 The bank that issues the bond as per 3.1 (b) here above shall **unequivocally guarantee to pay the purchaser immediately upon the first written demand of payment**. The purchaser's written demand of payment shall not be subject to any condition whatsoever.
 - 3.3 The bond issuing bank shall clearly incorporate the content stated under the clause here above on the issued bond.

3.4 Sealed bids shall be marked as: **“Tender for the Supply of Splicing Machine with RFQ No. 3529076-2”** and be addressed to:

**Ethio telecom
Head Quarter
Churchill Road
Sourcing and Facilities Division
2nd Floor, Room No. 214
P. O. Box 1047, Addis Ababa, Ethiopia**

4. Bid proposal will be received at the **Churchill Road, Head Quarter 2nd Floor, Room No. 214, before or on May 24, 2017 until 5:00 P.M.** Bids presented by any bidder after the closing date shall not be accepted.
5. Bids received in time and fulfilling the other formalities shall be opened in the presence of interested bidders or their legal representatives on **May 25, 2017 at 10:00 A.M, at Churchill Road, Head Quarter 2nd Floor, Room No. 213.**
6. Partial bid is **NOT** allowed.
7. Bidders are seriously advised to read and comply with the instructions provided in this bidding document.
8. No one is allowed to duplicate or transfer the bidding document that she/he acquired to participate under this invitation.
9. Ethio telecom reserves the right to reject all or parts of this bid.